

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claim 1 (currently amended): A testing apparatus comprising:

 a base controller comprising a plurality of first connectors that are connectable to a tester;
 a plurality of test controllers, each said test controller comprising a plurality of second
connectors that are connectable to an electronic device; and
 wireless means for communicating test data wirelessly between said base controller and
said test controllers.

Claim 2 (canceled)

Claim 3 (currently amended): The apparatus of claim 1, wherein at least a portion of one of said
test controllers is disposed on said electronic device.

Claim 4 (currently amended): ~~The apparatus of claim 1, wherein said testing apparatus further
comprises~~ A testing apparatus comprising:

a base controller comprising a plurality of first connectors that are connectable to a tester;
 a test controllers comprising a plurality of second connectors that are connectable to an
electronic device;
 wireless means for communicating test data wirelessly between said base controller and
said test controller; and
 an enclosure that is sealable, at least one of said base controller, test controller, or
wireless means disposed within said enclosure.

Claim 5 (original): The apparatus of claim 1, wherein said electronic device comprises a
semiconductor die.

Claim 6 (currently amended): The apparatus of claim 1 further comprising a plurality of said electronic devices, and wherein each said ~~[[die]]~~ electronic device comprises a semiconductor die, and said dies compose an unsingulated semiconductor wafer.

Claim 7 (currently amended): The apparatus of claim 1, wherein said wireless means comprises a first transceiver electrically connected to said test controller and ~~[[a]]~~ second transceivers electrically connected to said base controller.

Claim 8 (currently amended): ~~The apparatus of claim 1 further comprising~~ A testing apparatus comprising:

a base controller comprising a plurality of first connectors that are connectable to a tester;
a test controller comprising a plurality of second connectors that are connectable to an
electronic device; and

wireless means for communicating test data wirelessly between said base controller and
said test controller,

wherein said second connectors comprise a plurality of probes, each disposed to contact a terminal of said electronic device, ~~wherein said plurality of connectors that are connectable to said electronic devices are electrically connected to said probes.~~

Claim 9 (original): The apparatus of claim 1, wherein said test data includes at least one of test vectors or test commands.

Claims 10-13 (canceled)

Claim 14 (original): A test system comprising:

- a tester;
- a test station;
- a communications link between said tester and said test station; and
- a substrate disposed in said test station, said substrate comprising:
 - a base controller in communication with said communications link;
 - a plurality of test controllers each comprising a plurality of connectors that are connectable to one of a plurality of electronic devices to be tested; and
 - wireless means for communicating test data wirelessly between said base controller and said plurality of test controllers.

Claim 15 (original): The test system of claim 14, wherein at least a portion of one of said test controllers is disposed on one of said electronic devices.

Claim 16 (currently amended): The test system of claim 14, ~~further comprising~~ wherein said connectors comprise a plurality of probes, each disposed to contact a terminal of one of said electronic devices, ~~wherein said plurality of connectors that are connectable to one of said electronic devices are electrically connected to said probes.~~

Claim 17 (original): The test system of claim 14 further comprising a plurality of said testers, each in communication with said communications link.

Claim 18 (original): The test system of claim 17 further comprising a plurality of said test stations, each in communication with said communications link.

Claim 19 (original): The test system of claim 18, wherein said electronic devices are semiconductor dies.

Claim 20 (original): The test system of claim 19, wherein said semiconductor dies compose an unsingulated semiconductor wafer.

Claim 21 (original): The test system of claim 14, wherein said test data includes at least one of test vectors or test commands.

Claim 22 (original): The test system of claim 14 further comprising a cassette in which said substrate is disposed.

Claim 23 (original): The test system of claim 22, wherein said cassette is hermetically sealable.

Claim 24 (original): The test system of claim 14, wherein said substrate composes a probe card.

Claims 25-39 (canceled)